





(0,80 mm) .0315"

ERM8 SERIES

GGED HIGH SPEED HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?ERM8

Insulator Material: Black LCP

Terminal Material: Phosphor Bronze
Plating:
Au or Sn over

50μ" (1,27 μm) Ni Current Rating: 2.2 A per per pin (1 pin powered per row)
Operating Temp Range: ·55°C to +125°C Voltage Rating: 200 VAC max

RoHS Compliant: Yes

Processing: Lead-Free Solderable: Yes SMT Lead Coplanarity: (0,10 mm) .004" max (005-030) (0,12 mm) .005" max (040-060) (0,15 mm) .006" max (070-075)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality





Board Mates:

Cable Mates:

Single-Ended Signaling

ERM8

SERIES

(1,10) .043

U

ASP-137972-01 ERM8-DV

ASP-130365-01 ERM8-DV

23 ASP-130366-01 ERM8-DV

35 |ASP-135020-01 | ERM8-DV

В

ERCD, ERDF

MATED HEIGHT*						
ERM8	ERF8 LEAD STYLE					
LEAD STYLE	-05.0	-07.0				
-02.0	(7,00) .276	(9,00) .354				
-05.0	(10,00) .394	(12,00) .472				
-08.0	(13,00) .512	(15,00) .591				
-09.0	(14,00) .551	(16,00) .629				
*Processing conditions will affect mated height.						

ERM8/ERF8 7 mm Stack Height		with PCB effects	8*	w/o PCB effec	
		Rated @ 3dB Insertion Loss			
*Processing conditions will affect mated height.					
-09.0	(14,00) .551	(16,00) .629			
-08.0	(13,00) .512	(15,00) .591		73	
-05.0	(10,00) .394	(12,00) .472			
-02.0	(7,00).276	(9,00) .354		734	

Differential Pair Signaling	9.5 GHz / 19 Gbps	15.5 GHz / 31 Gb			
*Performance data includes effects of a non-optimized PCB.					
**Test board losses de-embedded from performance data.					

Performance data for other stack heights and complete test data available at www.samtec.com?ERM8 or contact sig@samtec.com

POSITIONS

PER ROW

Designed for Rugged Hot Swap Micro pitch applications option EXTENDED LIFE PRODUCT 10 year Mixed Flowing Gas with 30μ" Gold Call Samtec for maximum mated cycles (1.50 mm) NOMINAL WIPE cts** 10.5 GHz / 21 Gbps 12 GHz / 24 Gbps

ERTIFIED

PLATING

OPTION

= 10µ"

(0,25 µm)

Gold on

contact,

Matte Tin

on tail

·S

= 30µ"

Gold on

contact,

on tail

DV **OTHER OPTION**

=Tape & Reel

Packaging



-100(Available with -09.0 lead style only)



(0,80)

224 (0,76 µm) **Matte Tin** (7,20).283°_I ਹੋਰ -EGPS

LEAD

STYLE

No. of Positions x (0,80) .0315 + (6,00) .236 (10,80)-L & -EGP = No. of Positions x425 (0.80) .0315 + (9.00) .354-EGPS = No. of Positions x (0.80) .0315 + (10.00) .394-EGP (3,25)(5,60) .128 .220 (3,20).126 (1,07)

052

-02.0 (1,61) .063 (5,97) .235 **-05.0** (4,61) .181 (8,91) .351 **-08.0** (7,61) .300 (11,91) .469 **-09.0** (8,61) .339 (12,91) .508 Note: Patented

APPLICATIONS

NEXUS5001™.org 11 ASP-137968-01 ERM8-DV

STANDARD POS. PART NOs.

17

20

POWER.org

ARM/HSSTP

POWER.org

NEXUS5001™.org

Note: Some lengths, styles and options are non-standard, non-returnable.



= Differential Pair (-05.0 lead style only) (-010, -013, -025, -049 Positions only)

= (4,00 mm) .157" DIA Polyimide Film Pick & Place Pad

= Latching (-05.0 lead styles only) (Not available with -EGP & -EGPS options)

-EGP
= Extended Guide Post
(-05.0 lead style only)
(Not available with -L option)

-EGPS

= Extended Guide Post Shield
(-05.0 lead style only)
(-010, -020, -025, -030 Positions only)
(Not available with -L option)

= Differential Pair + Extended Guide Post (-05.0 lead styles only) (-013 & -025 Positions only)

= Differential Pair + Extended Guide Post Shield (-05.0 lead styles only) (–025 positions only)

.042

(5,60)